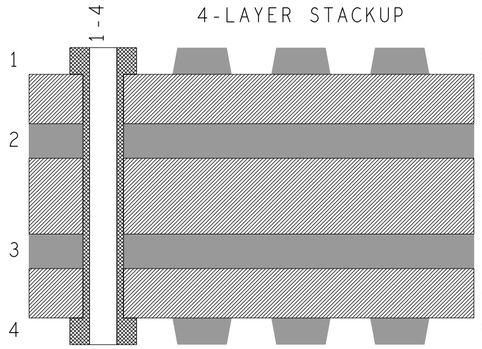
REVISIONS			
REV	DESCRIPTION	DATE	APPROVED
A	INITIAL RELEASE	05APR23	I.ANDAL
B	AS PER ECR-117976	11MAR24	I.SANTOS
C	AS PER ECR-121828	12AUG24	I.SANTOS

4-LAYER STACKUP

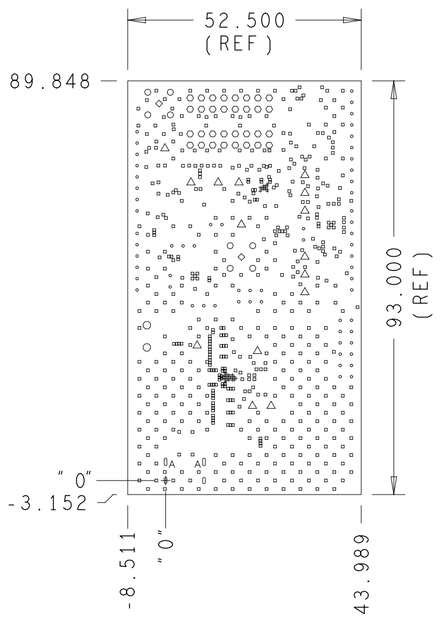


1	COPPER	0.018 MM
	370HR	0.1778 MM
2	1OZ_COPPER	0.036 MM
	370HR	1.08712 MM
3	1OZ_COPPER	0.036 MM
	370HR	0.1778 MM
4	COPPER	0.018 MM

PRIMARY: 1.600 MM

HOLE TOLERANCE

UNLESS SPECIFIED
PLATED: +/- .0762 MM
NON PLATED: +/- .0508 MM



DRILL CHART: TOP to BOTTOM					
ALL UNITS ARE IN MILLIMETERS					
FIGURE	SIZE	PLATED	QTY	TOLERANCE/NOTES	
·	0.127	PLATED	38	DIA MAX	SEE NOTE #20
▫	0.2032	PLATED	578	DIA MAX	SEE NOTE #20
○	1.016	PLATED	32		
◦	1.143	PLATED	62		
◇	1.1684	PLATED	2		
○	1.27	PLATED	2		
△	1.6002	PLATED	15		
○	1.7018	PLATED	8		
A	0.6604	NON-PLATED	2		
▯	1.397x0.6096	PLATED	2		
▯	1.7018x0.6096	PLATED	2		

PRIMARY SIDE

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MM TOLERANCES DECIMALS FRACTIONS ANGLES .XX +-.010 +-1/32 +- 2 .XXX +-.005 .XXXX +-.0050	APPROVAL	DATE	ANALOG DEVICES WWM DIVISION 804 WOBURN STREET WILMINGTON, MA 01887			
	TEMPLATE ENGINEER N/A	N/A				
	HARDWARE SERVICES M.VALE	05APR23				
	HARDWARE SYSTEMS N/A	N/A				
MATERIAL	TEST ENGINEER N/A	N/A	TITLE FABRICATION EVAL-AD3530RARDZ			
	COMPONENT ENGINEER N.CATALAN	29JAN24				
	TEST PROCESS N/A	N/A				
	HARDWARE RELEASE K.JABATAN	05APR23				
FINISH	DESIGNER N.CORDOVA	05APR23	SIZE	FSCM NO	DRAWING NUMBER	REV
	PTD ENGINEER I.ANDAL	05APR23	C	24355	09-071775	C
	CHECKER N/A	N/A				
DO NOT SCALE DWG			SCALE 1/1		SHEET 1 OF 2	

NOTES: UNLESS OTHERWISE SPECIFIED

1. DIMENSIONS ARE IN MM (EXCEPT WHERE NOTED).
ALL DOCUMENTS & SPECIFICATIONS REFERRED TO BELOW SHOULD BE THE LATEST REVISIONS.

MATERIAL: HOMOGENOUS MATERIALS IN THIS BOARD SHALL BE COMPLAINT WITH THE EU DIRECTIVE 2002/95/EC

2. BOARD MATERIAL:(USE CHECKED ITEMS)
(X) ISOLA 370HR OR S1000-2 OR IT180 OR EQUIVALENT
( ) ISOLA FR408HR OR EQUIVALENT
( ) ISOLA IS410
( ) MEGTRON 6
( ) NELCO 4000-13
( ) ROGERS 4350B
( ) ROGERS 3003
( ) ARLON 85N
( ) EM370D
( ) OTHER _____

3. ALL LAMINATES & BONDING MATERIALS SHOULD BE SELECTED FROM IPC-4101 OR IPC-4103,(TG>170 DEGC TD>300 DEGC)
UL FLAMMABILITY RATING 94V-0. BOARD MATERIAL & CONSTRUCTION SHALL MEET THE REQUIREMENTS OF UL796/UL796F.
4. REFER TO IPC-6010 SERIES, CLASS 2 FOR FABRICATION.WORKMANSHIP SHALL CONFORM TO IPC-A-600, CLASS 2.
5. REFER TO LAMINATION DIAGRAM FOR OVERALL BOARD THICKNESS, TOLERANCE APPLIES AFTER ALL LAMINATION AND PLATING PROCESSES. FINISHED THICKNESS MEASURED FROM TOP COPPER TO BOTTOM COPPER.
6. BOW & TWIST NOT TO EXCEED 0.0075 INCHES (0.75%) PER LINEAR INCH AND SHOULD BE MEASURED PER IPC-TM-650, METHOD 2.4.22.
7. ACCEPTABILITY PER ADI SPECIFICATION TST00115.

TOOLING:

8. IMPEDANCE REQUIREMENTS: IF NO STACKUP IS DEFINED, THE VENDOR IS ALLOWED TO ADJUST THE DIELECTRIC THICKNESS & TRACE WIDTHS TO MEET THE IMPEDANCE REQUIREMENT. IF SPECIFIED, THE VENDOR MUST MEET THE REQUIREMENTS LISTED IN THE IMPEDANCE TABLE. ANY ADJUSTMENT MADE TO THE DEFINED STACKUP, TRACE WIDTH & SPACING THAT IMPACT THE REQUIREMENTS MUST HAVE WRITTEN APPROVAL FROM ADI.
9. FILLET OPTIONS TO ENHANCE RELIABILITY AT PAD JUNCTIONS WHERE SPACING PERMITS.
( ) FILLETS ALLOWED
(X) FILLETS NOT ALLOWED
10. THIEVING:
( ) VENDOR MAY ADD THIEVING TO COMPENSATE FOR LOW COPPER DENSITY AREAS MAINTAINING A MINIMUM 2.54 MM CLEARANCE FROM ALL COPPER FEATURES,
(X) VENDOR MAY NOT ADD THIEVING TO COMPENSATE FOR LOW COPPER DENSITY AREAS.
11. LAYER TO LAYER REGISTRATION SHALL BE WITHIN 0.0762 MM.

FINISH:

12. DRILL SIZES ARE FINISHED HOLE SIZES. ALL HOLES SHALL BE LOCATED WITHIN 0.127 MM DTP, MINIMUM BARREL PLATING OF 0.0254 MM. PLATED HOLES SHALL NOT BE ROUGH OR IRREGULAR SO AS TO HINDER PROPER SOLDER WICKING. BARREL RELIEF ON SOLDERMASK ALLOWED IN UNFILLED VIA IN PAD HOLES.
13. PLATING SPECIFICATION:
(X) REFER TO LAMINATION DIAGRAM FOR FINISHED COPPER WEIGHT/THICKNESS REQUIRMENTS
THE STARTING COPPER WEIGHT/THICKNESS CAN VARY AS LONG AS THE FINISHED COPPER WEIGHT/THICKNESS IS NOT LESS THAN THE SPECIFIED VALUE.
14. SURFACE FINISH:
(X) IMMERSION GOLD (ENIG) 1.58-3.94 MICRO INCHES OVER 118-236 MICRO INCHES MIN. OF ELECTROLESS NICKEL PER IPC-4552
( ) OSP (ORGANIC SOLDERABILITY PRESERVATIVE)
( ) IMMERSION SILVER
( ) SOFT WIRE BONDABLE GOLD 30-50 MICRO INCHES OF SOFT WIRE BONDABLE GOLD OVER 100-150 MICRO INCHES OF NICKEL
( ) EDGE CONNECTOR FINGERS ARE TO BE PLATED WITH 100 MICRO-INCHES(.0001") OF LOW STRESS NICKEL UNDER 30 MICRO-INCHES (.0003') OF GOLD
( ) OTHER_____
15. SOLDERMASK:
SOLDERMASK OVER BARE COPPER OR BARE GOLD (BOTH SIDES) TO MEET IPC-SM-840.
IF PRESENT,DO NOT MODIFY SOLDERMASK DEFINED PADS (MASK OPENINGS LESS THAN COPPER PAD) WITHOUT APPROVAL.
(X) LPI
( ) OTHER_____

COLOR
(X) GREEN
( ) OTHER_____

16. APPLY SILKSCREEN TO BOTH SIDES USING A NON-CONDUCTIVE, EPOXY BASED INK PER ARTWORK.
(X) WHITE
( ) OTHER

TESTING:

17. FINAL ELECTRICAL TEST TO BE PERFORMED USING PROVIDED IPC-D-356A NETLIST OR ODB++ FORMAT FILE. THE PCB SHALL HAVE A VERIFICATION STAMP.
18. A TIME DOMAIN REFLECTOMETER REPORT (TDR) FOR EACH IMPEDANCE CONTROLLED LAYER & A CERTIFICATE OF COMPLIANCE SHALL BE PROVIDED BY VENDOR AT TIME OF SHIPMENT. INSTANCES WHERE TDR TESTING CAN'T BE PERFORMED BECAUSE THE TRACE LENGTH IS TOO SHORT ON THE OUTER LAYERS AT THE PIN ESCAPES IS ACCEPTABLE, ALL OTHER INSTANCES MUST BE REPORTED.

MISCELLANEOUS:

19. IF PRESENT, ALL BLIND/BURIED VIAS WITH AN ASPECT RATIO <1:1 TO BE PLATED SHUT WITH COPPER WHEN USED AS VIA-IN-PAD OR AS A STACKED VIA. BLIND/BURIED VIAS WITH AN ASPECT RATIO >1:1 TO BE FILLED WITH NON-CONDUCTIVE EPOXY.
20. FOR VIA FILL INFORMATION REFER TO DRILL CHART:
(X) NON-CONDUCTIVE EPOXY FILL DRILLED VIAS
( ) COPPER FILL DRILLED VIAS
21. INTENTIONAL SHORTS:
IF AN INTENTIONAL SHORT REPORT IS SUPPLIED AND DOES NOT MATCH THE FAB DATA THEN ADI APPROVAL IS REQUIRED.
22. PEMNUTS:
( ) PEMNUTS TO BE INSTALLED BY FABRICATOR
( ) PEMNUTS NOT TO BE INSTALLED BY FABRICATOR
(X) NOT APPLICABLE
23. MANUFACTURER TO ETCH/STAMP WITH PERMANENT NON-CONDUCTIVE INK ON SECONDARY SIDE UNLESS OTHERWISE SPECIFIED:
A. UL CODE-FLAMMABILITY RATING FOR THOSE APPROVED MATERIALS(IF APPLICABLE)
B. DATE CODE
C. LOT NUMBER
D. MANUFACTURER LOGO
24. PANELIZATION:
BOARDS TO BE SHIPPED IN ARRAY AND KEPT INTACT
PANEL TO BE SUBJECTED TO CUSTOMERS APPROVAL
PANEL SOLDER PASTE STENCIL GERBER TO BE PROVIDED TO ANALOG
25. MINIMUM DESIGN LINE WIDTH IS .1524MM.
26. MINIMUM DESIGN LINE SPACING IS .0796 MM.

FAB NOTES REVISION: 2ND NOVEMBER 2022

PRIMARY SIDE

ANALOG DEVICES
WWM
DIVISION
804 WOBURN STREET
WILMINGTON, MA 01887

SIZE	FSCM NO	DRAWING NUMBER	REV
C	24355	09-071775	C
SCALE 1/1			SHEET 2 OF 2